



Docket No.: M4065.0468/P468  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Phillip E. Byrd, et al.

Application No.: 09/941,761

Allowed: May 20, 2003

Filed: August 30, 2001

Group Art Unit: 2812

For: STRUCTURE FOR TEMPORARILY  
ISOLATING A DIE FROM A  
COMMON CONDUCTOR TO  
FACILITATE WAFER LEVEL  
TESTING (AS AMENDED HEREIN)

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Examiner: A. Stevenson

**AMENDMENT UNDER 37 CFR § 1.312**

Attn: Box Issue Fee  
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

Prior to issuance, please amend the above-captioned application as follows:

Amendments to the Specification begin on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.